



**PRODUCT/PROCESS
CHANGE NOTIFICATION
PCN– Additional information**

**ASE Kaohsiung (Taiwan) additional source
For TFBGA14x14 240b for STM32H75 2MB products**

MDG - Microcontrollers Division (MCD)

What are the changes?

Changes described in table below:

	Existing back-end site	Added back-end site
Assembly site	AMKOR ATP (Philippines)	ASE Kaohsiung (Taiwan)
Die Attach Material	Ablebond 2300	ATB-125
Molding compound (1)	GE100LFCS	KE-G1250AAS
Ball material	SAC105	SACN305
POA (2)		
Max package thickness	1.1mm	1.2mm
Min Ball diam after reflow	0.350mm	0.320mm

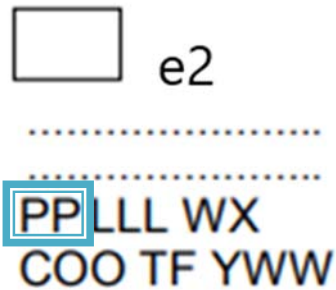
(1) Package darkness changes depending on molding compound.

(2) All other Package Outline Assembly (POA) dimensions remain unchanged.

Note: Pin1 identifier can change in terms of form and positioning.
Marking position and size could be different upon assembly site, without any loss of information.

How can the change be seen?

The standard marking is:



PP code indicates assembly traceability plant code.

Please refer to DataSheet for marking details.

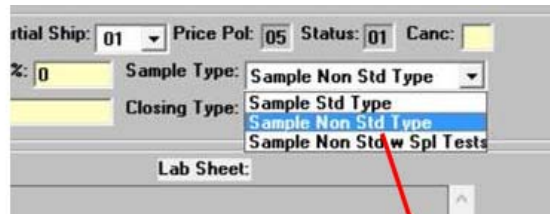
The marking is changing as follows:

Existing		Additional	
PP code	Fab	PP code	Fab
7B	Amkor ATP Philippines	AA	ASE Kaohsiung Taiwan

How to order samples?

For all samples request linked to this PCN, please:

- place a **Non-standard** sample order (choose Sample Non Std Type from pull down menu)
- insert the PCN number “**PCN11190**” into the NPO Electronic Sheet/**Regional Sheet**
- request sample(s) through Notice tool, indicating a single Commercial Product for each request



Partial Ship: 01 Price Pol: 05 Status: 01 Canc: ☐

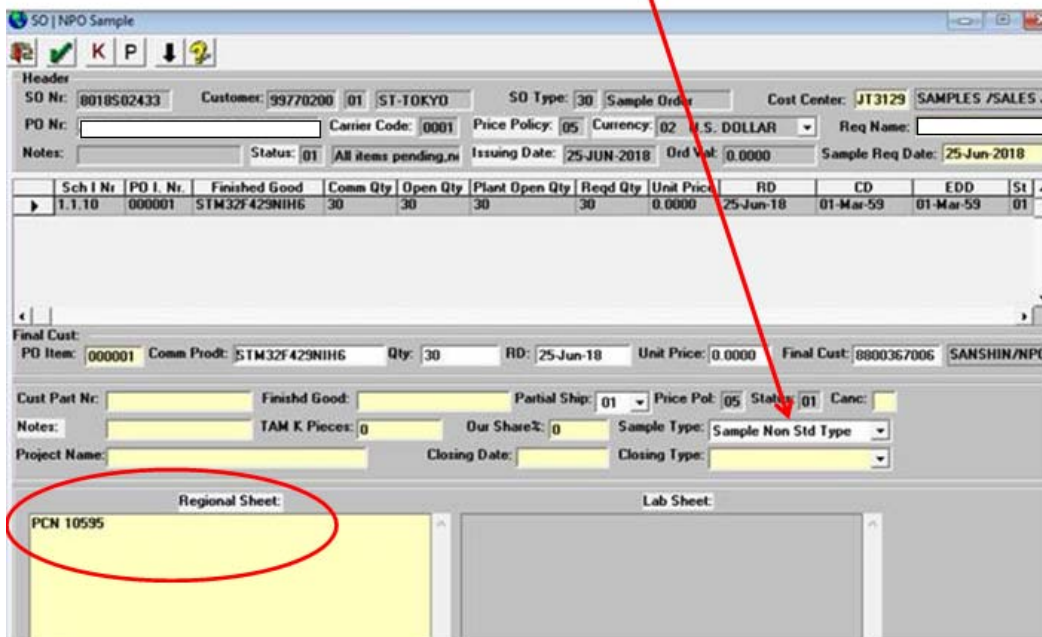
%: 0 Sample Type: Sample Non Std Type

Closing Type: Sample Std Type

Sample Non Std Type

Sample Non Std w Spl Tests

Lab Sheet:



SO | NPO Sample

Header

SO Nr: 0018502433 Customer: 99770200 01 ST-TOKYO SO Type: 30 Sample Order Cost Center: JT3129 SAMPLES /SALES J

PO Nr: Carrier Code: 0001 Price Policy: 05 Currency: 02 U.S. DOLLAR Req Name:

Notes: Status: 01 All items pending.ri Issuing Date: 25-JUN-2018 Ord Val: 0.0000 Sample Req Date: 25-Jun-2018

Sch I Nr	PO I. Nr.	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St
1.1.10	000001	STM32F429NIH6	30	30	30	30	0.0000	25-Jun-18	01-Mar-59	01-Mar-59	01

Final Cust: PD Item: 000001 Comm Prod: STM32F429NIH6 Qty: 30 RD: 25-Jun-18 Unit Price: 0.0000 Final Cust: 8800367006 SANSIHN/NP

Cust Part Nr: Finishd Good: Partial Ship: 01 Price Pol: 05 Status: 01 Canc: ☐

Notes: TAM K Pieces: 0 Our Share: 0 Sample Type: Sample Non Std Type

Project Name: Closing Date: Closing Type:

Regional Sheet: PCN 10595

Lab Sheet:



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**RERMCD2011 for
PCN12190
ASE Kaohsiung (Taiwan)
additional source for
TFBGA 14x14**

June 24th, 2020

MDG MCD Quality & Reliability Department

RERMCD2011 ASE Kh (Taiwan) additional source for TFBGA 14X14 - Package Test Vehicle

Package line	Assembly Line	Package	Device (Partial RawLine Code)	Diffusion Plants & Process	Number of Reliability Lots
BGA	TFBGA 14x14	265 balls	CV*450	ST Crolles M40	3

RERMCD2011 ASE Kh (Taiwan) additional source for TFBGA 14x14 - Package Reliability Trials

Reliability Trial & Standard		Test Conditions	Pass Criteria	Unit per Lot	Lot qty
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	231	3
TC (*)	Thermal Cycling JESD22 A104	-50°C, +150°C Or equivalent -65°C +150°C	1000Cy 500Cy	77	3
THB (*)	Temperature Humidity Bias JESD22-A101	85°C, 85% RH, bias	1000h	77	3
HTSL (*)	High Temperature Storage Life JESD22 A103	150°C- no bias	1000h	77	3
Construction analysis	JESD 22B102 JESDB100/B108			50	3
ESD	ESD Charge Device Model ANSI/ESD STM5.3.1	Aligned with device datasheet	250V	3	1

(*) tests performed after preconditioning

Thank you

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